

2SK0615 (2SK615)

Silicon N-Channel MOS FET

For switching

■ Features

- Low ON-resistance
- High-speed switching
- Allowing to be driven directly by CMOS and TTL
- M type package, allowing easy automatic and manual insertion as well as stand-alone fixing to the printed circuit board.

■ Absolute Maximum Ratings (Ta = 25°C)

Parameter	Symbol	Ratings	Unit
Drain to Source voltage	V_{DS}	80	V
Gate to Source voltage	V_{GS0}	20	V
Drain current	I_D	± 0.5	A
Max drain current	I_{DP}	± 1	A
Allowable power dissipation	P_D^*	1	W
Channel temperature	T_{ch}	150	°C
Storage temperature	T_{stg}	-55 to +150	°C

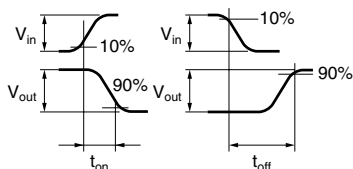
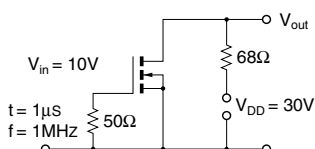
* PC board: Copper foil of the drain portion should have an area of 1cm² or more and the board thickness should be 1.7mm.

■ Electrical Characteristics (Ta = 25°C)

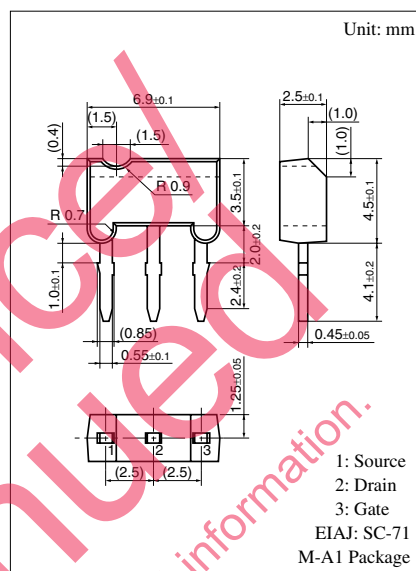
Parameter	Symbol	Conditions	min	typ	max	Unit
Drain to Source cut-off current	I_{DSS}	$V_{DS} = 60V, V_{GS} = 0$			10	μA
Gate to Source leakage current	I_{GSS}	$V_{GS} = 20V, V_{DS} = 0$			0.1	μA
Drain to Source breakdown voltage	V_{DSS}	$I_D = 100\mu A, V_{GS} = 0$	80			V
Gate threshold voltage	V_{th}	$I_D = 1mA, V_{DS} = V_{GS}$	1.5		3.5	V
Drain to Source ON-resistance	$R_{DS(on)}^{*1}$	$I_D = 0.5A, V_{GS} = 10V$		2	4	Ω
Forward transfer admittance	$ Y_{fs} $	$I_D = 0.2A, V_{DS} = 15V, f = 1kHz$		300		mS
Input capacitance (Common Source)	C_{iss}	$V_{DS} = 10V, V_{GS} = 0, f = 1MHz$		45		pF
Output capacitance (Common Source)	C_{oss}			30		pF
Reverse transfer capacitance (Common Source)	C_{rss}			8		pF
Turn-on time	$t_{on}^{*1, 2}$			15		ns
Turn-off time	$t_{off}^{*1, 2}$			20		ns

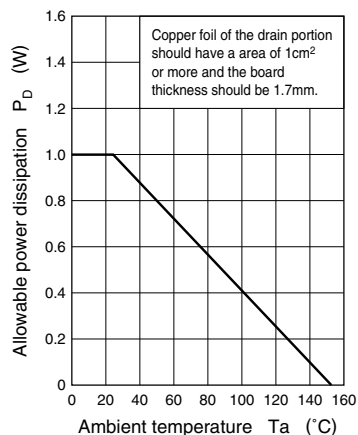
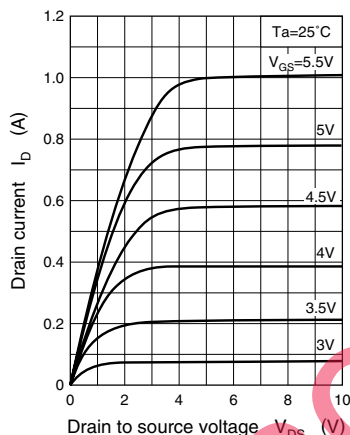
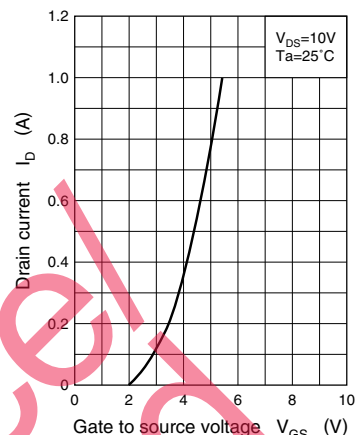
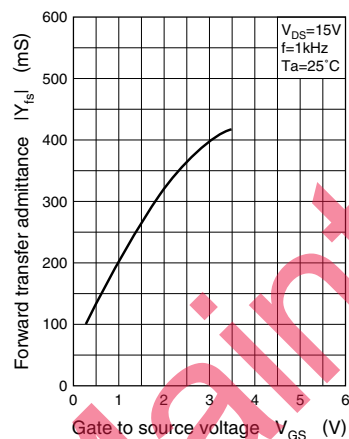
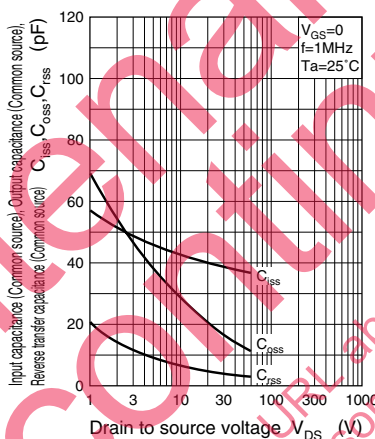
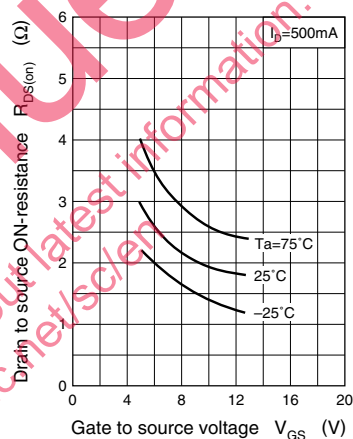
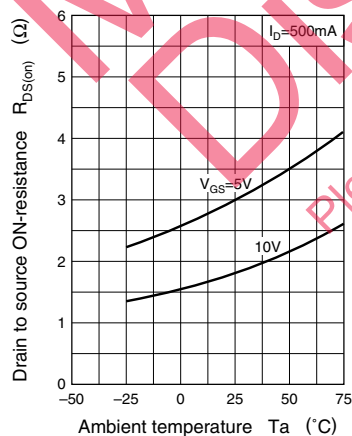
*1 Pulse measurement

*2 t_{on}, t_{off} measurement circuit



Note) The part number in the parenthesis shows conventional part number.



$P_D - T_a$  $I_D - V_{DS}$  $I_D - V_{GS}$  $|Y_{fs}| - V_{GS}$  $C_{iss}, C_{oss}, C_{rss} - V_{DS}$  $R_{DS(on)} - V_{GS}$  $R_{DS(on)} - T_a$ 

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